

(0.80 mm) .0315"

TEM, TEMS, TEM-DH SERIES

MICRO TIGER EYE™ HEADER

TEM, TEM-DH Mates with:

SEM, SEML

TEMS Mates with:

SEMS

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?TEM or www.samtec.com?TEMS

Insulator Material:

Black Liquid Crystal Polymer

Terminal Material:

Phosphor Bronze

Plating:

Au or Sn over

50 μ" (1.27 μm) Ni

Current Rating:

2.9 A per pin

(2 pins powered)

Voltage Rating:

235 VAC/330 VDC

Operating Temp Range:

-55 °C to +125 °C

RoHS Compliant:

Yes

PROCESSING

Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

(0.10 mm) .004" max

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



FILE NO. E111594

OTHER SOLUTIONS

- Latching option: See TEM-L1 in Discrete Wire Cable section.
- Board Stacking: See SFM, TFM Series
- Cable Assemblies: See SFSD, TFSD, SESDT Series

ALSO AVAILABLE (MOQ Required)

- Other sizes
- Other platings

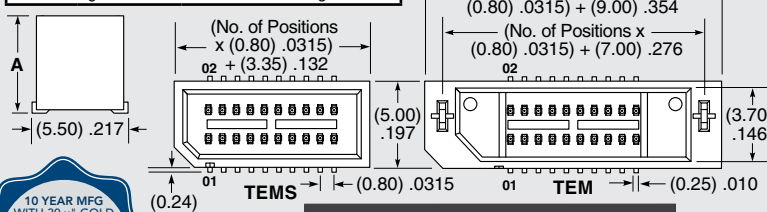
Note:

Some sizes, styles and options are non-standard, non-returnable.

TYPE STRIP	1	NO. OF POSITIONS	02	STACK HEIGHT	PLATING OPTION	D	OPTION	OTHER OPTION
TEM = Tiger Eye™ Strip		05, 10, 15, 20, 25 (Per Row)		-03.0 = 6 mm Stack Height	-FG = Gold Flash		Leave blank for TEMS	-K = (5.50 mm) .217" DIA Polyimide film Pick & Place Pad (Required for TEMS)
TEMS = Tiger Eye™ Slim Strip		30, 35, 40, 45, 50 (Per Row) (TEM only) (Standard sizes)		-04.0 = 7 mm Stack Height	-G = 10 μ" (0.25 μm) Gold on contact, Gold Flash on tail		-A = Alignment Pin (Not available with -LC or -WT)	-TR = Tape & Reel (Required for TEMS)
				-07.0 = 10 mm Stack Height	-H = 30 μ" (0.76 μm) Gold on contact, Gold Flash on tail		-LC = Locking Clip (Not available with -A or -WT) (Manual placement required)	
							-WT = Weld Tab (Not available with -A or -LC)	

STACK HEIGHT	A	MATED HEIGHT* (WHEN MATED WITH SEM/SEMS)
-03.0	(5.610) .2209	6 mm
-04.0	(6.610) .2602	7 mm
-07.0	(9.610) .3783	10 mm

*Processing conditions will affect mated height.



HIGH-SPEED CHANNEL PERFORMANCE

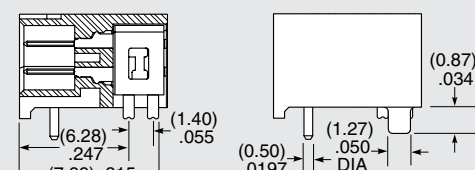
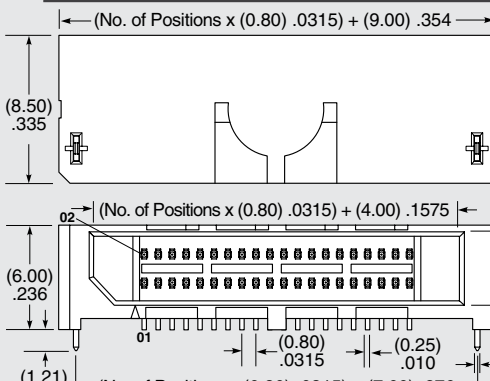
Rating based on Samtec reference channel. For full SI performance data visit Samtec.com or contact SIG@samtec.com

8 Gbps

POWER/SIGNAL APPLICATION



TEM	1	NO. OF POSITIONS	02	DH1	PLATING OPTION	D	OPTION
		10, 15, 20, 25, 30, 35, 40, 45, 50 (Per Row) (Standard sizes)			-F = Gold Flash on contact, Matte Tin on tail		-A = Alignment Pin
					-L = 10 μ" (0.25 μm) Gold on contact, Matte Tin on tail		
					-S = 30 μ" (0.76 μm) Gold on contact, Matte Tin on tail		



Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM

All parts within this catalog are built to Samtec's specifications.

Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.